



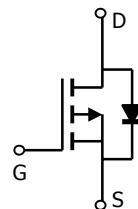
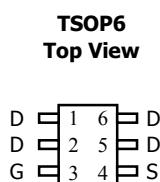
AO6403 P-Channel Enhancement Mode Field Effect Transistor

General Description

The AO6403 uses advanced trench technology to provide excellent $R_{DS(ON)}$, and ultra-low low gate charge. This device is suitable for use as a load switch or in PWM applications. It may be used in common-drain configuration to form a bidirectional blocking switch.

Features

V_{DS} (V) = -30V
 I_D = -6 A
 $R_{DS(ON)} < 35m\Omega$ ($V_{GS} = -10V$)
 $R_{DS(ON)} < 58m\Omega$ ($V_{GS} = -4.5V$)



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^A	I_D	-6	A
$T_A=70^\circ C$		-5	
Pulsed Drain Current ^B	I_{DM}	-30	
Power Dissipation ^A	P_D	2	W
$T_A=70^\circ C$		1.44	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	47.5	62.5	°C/W
Steady-State		74	110	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	37	50	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$	$T_J=55^\circ\text{C}$	-1	-5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.2	-2	-2.4	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	30			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-6\text{A}$	$T_J=125^\circ\text{C}$	28	35	$\text{m}\Omega$
				37	45	
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-6\text{A}$		13		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.76	-1	V
I_S	Maximum Body-Diode Continuous Current				-4.2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		920		pF
C_{oss}	Output Capacitance			190		pF
C_{rss}	Reverse Transfer Capacitance			122		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		3.6		Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-6\text{A}$		18.5		nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)			9.6		nC
Q_{gs}	Gate Source Charge			2.7		nC
Q_{gd}	Gate Drain Charge			4.5		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=2.7\Omega, R_{\text{GEN}}=3\Omega$		7.7		ns
t_r	Turn-On Rise Time			5.7		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			20.2		ns
t_f	Turn-Off Fall Time			9.5		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		20		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		8.8		nC

A: The value of R_{0JA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R_{0JA} is the sum of the thermal impedance from junction to lead R_{0JL} and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

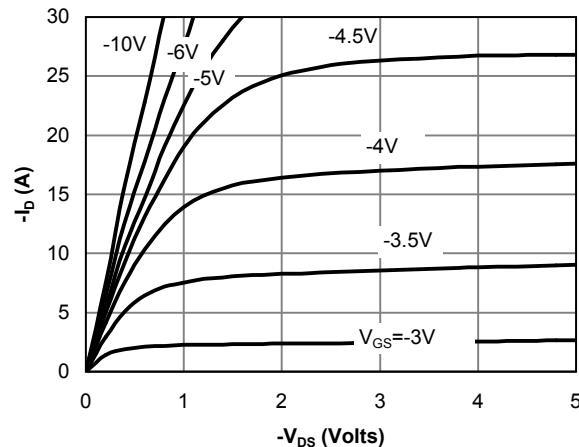


Fig 1: On-Region Characteristics

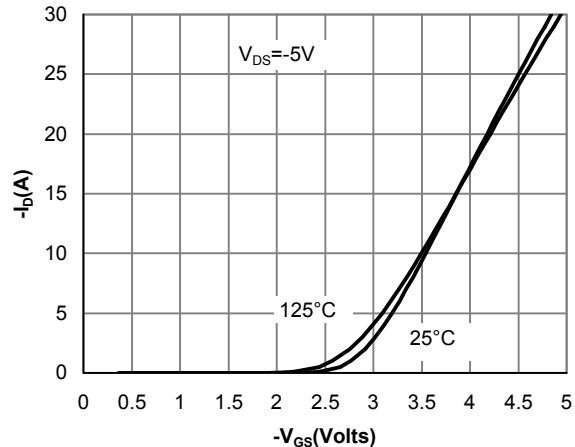


Figure 2: Transfer Characteristics

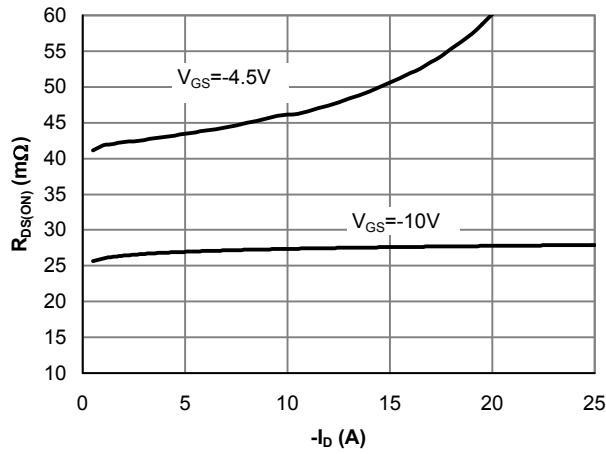


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

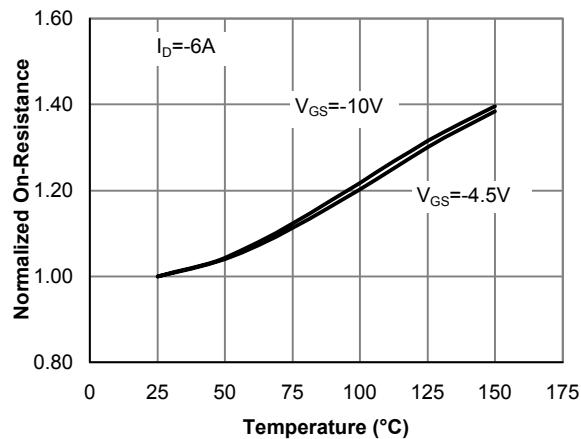


Figure 4: On-Resistance vs. Junction Temperature

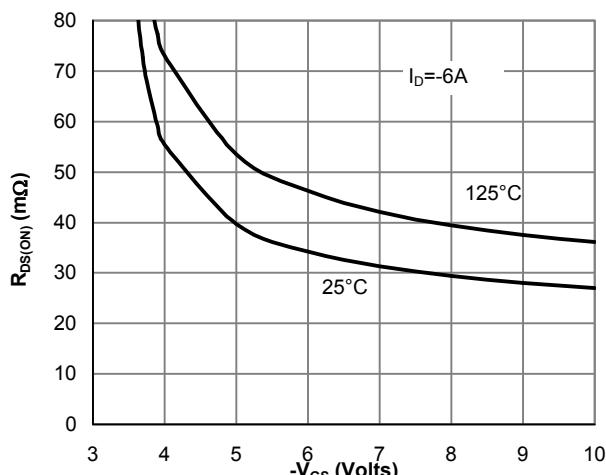


Figure 5: On-Resistance vs. Gate-Source Voltage

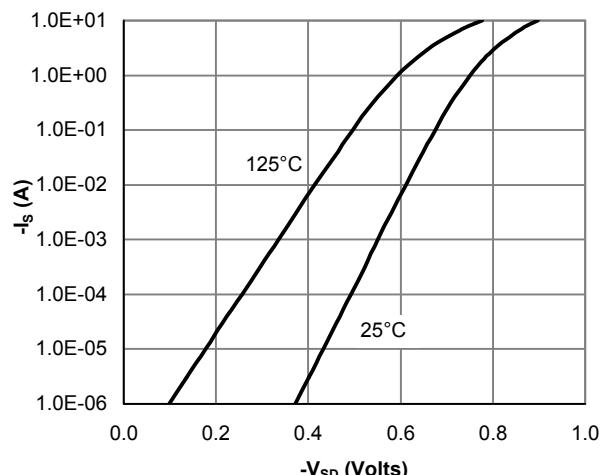


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

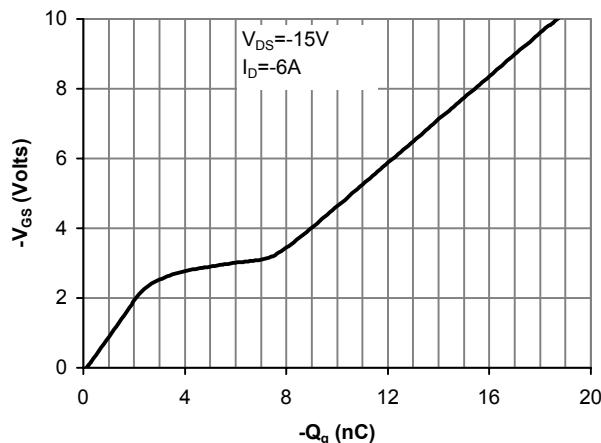


Figure 7: Gate-Charge Characteristics

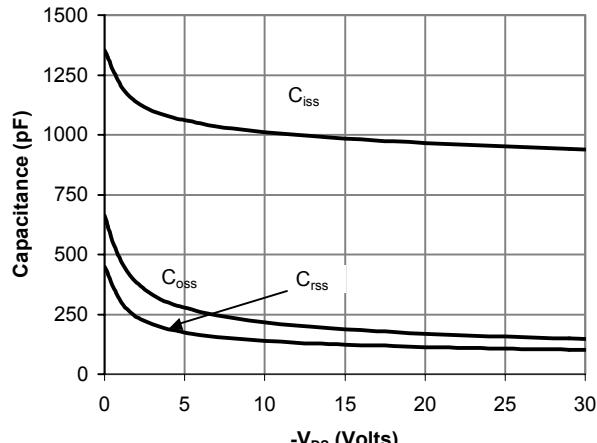


Figure 8: Capacitance Characteristics

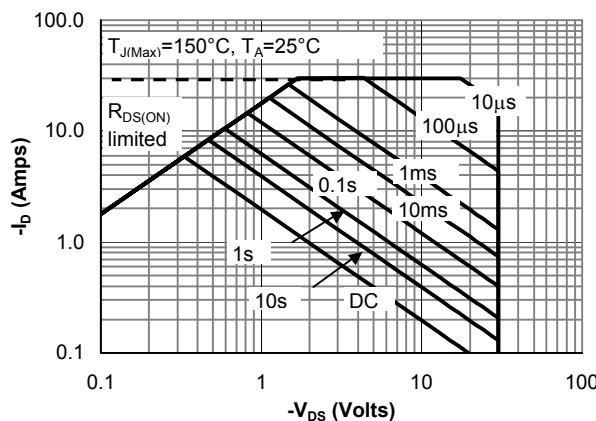


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

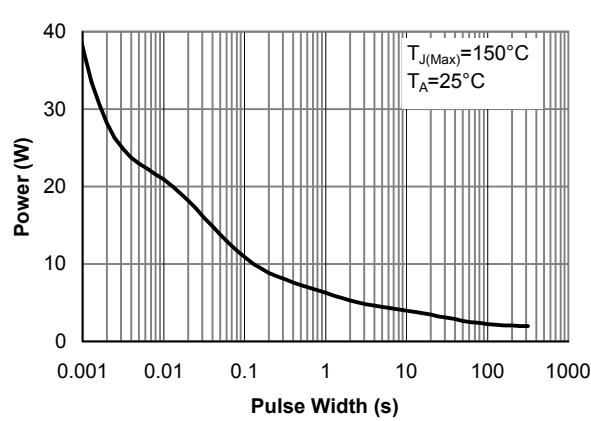


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

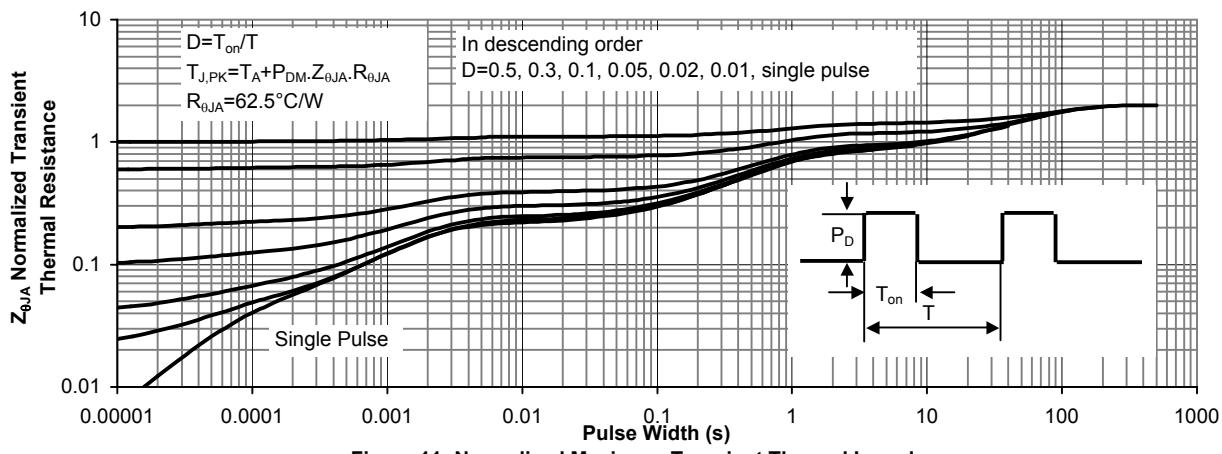
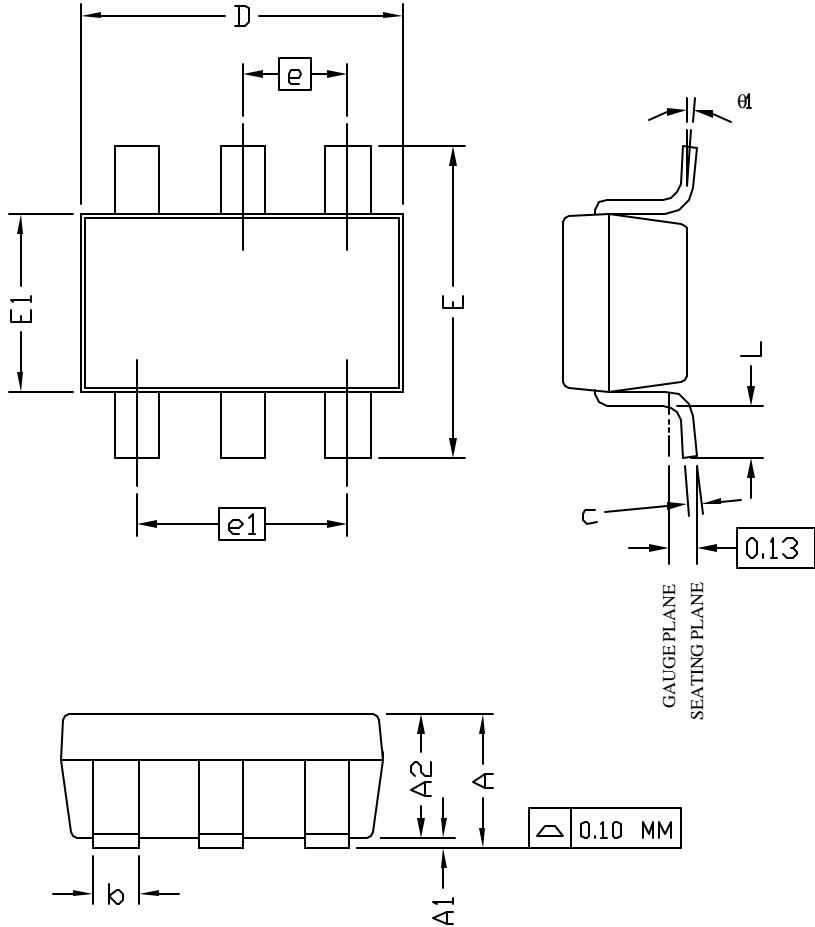


Figure 11: Normalized Maximum Transient Thermal Impedance



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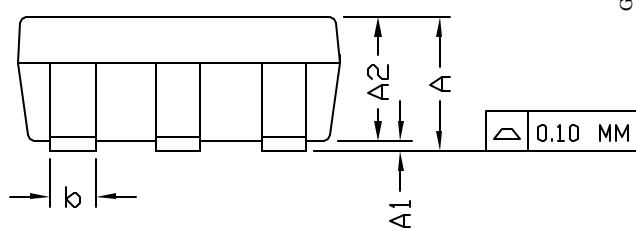
Document No.	PD-00099
Version	rev A
Title	AO6403 Package Data Sheet



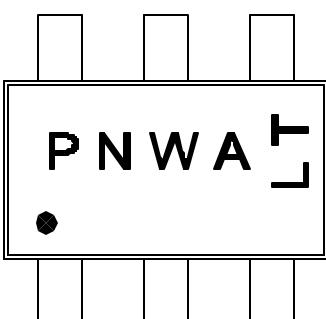
SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.00	—	1.25
A1	0.00	—	0.10
A2	1.00	1.10	1.15
b	0.35	0.40	0.50
c	0.10	0.13	0.20
D	2.70	2.90	3.10
E	2.60	2.80	3.00
E1	1.60	1.80	2.00
e	0.95 BSC		
e1	1.90 BSC		
L	0.37	—	—
θ1	1°	5°	8°

NOTE:

1. LEAD FINISH: 150 MICROINCHES (3.8 um) MIN.
THICKNESS OF Tin/Lead (SOLDER) PLATED ON LEAD
2. TOLERANCE ± 0.100 mm (4 mil) UNLESS OTHERWISE SPECIFIED
3. COPLANARITY : 0.1000 mm
4. DIMENSION L IS MEASURED IN GAGE PLANE



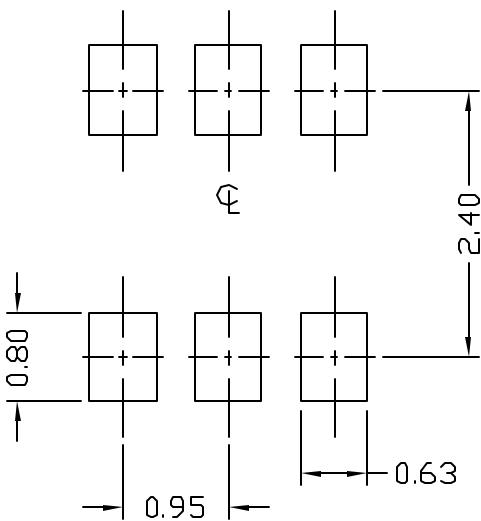
PACKAGE MARKING DESCRIPTION



TSOP-6 PART NO. CODE

PART NO.	CODE
AO6403	D3

RECOMMENDED LAND PATTERN



NOTE:

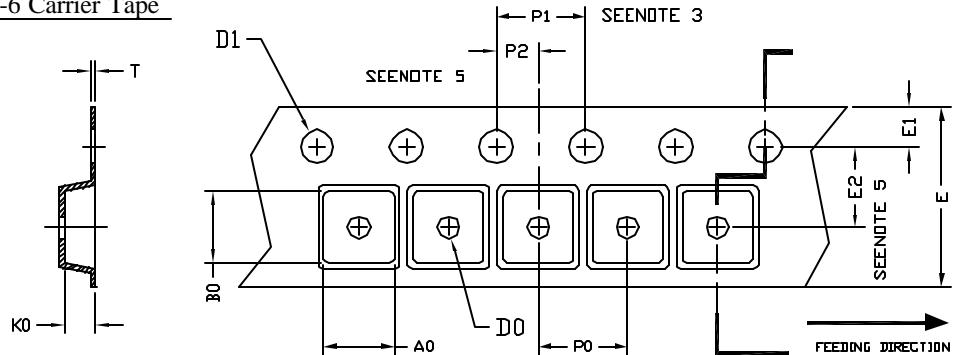
P - Package and product type.
N - Last digital of product number.
W - Week code
A - Foundry location code
LT - Assembly lot code.



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TSOP-6 Tape and Reel Data

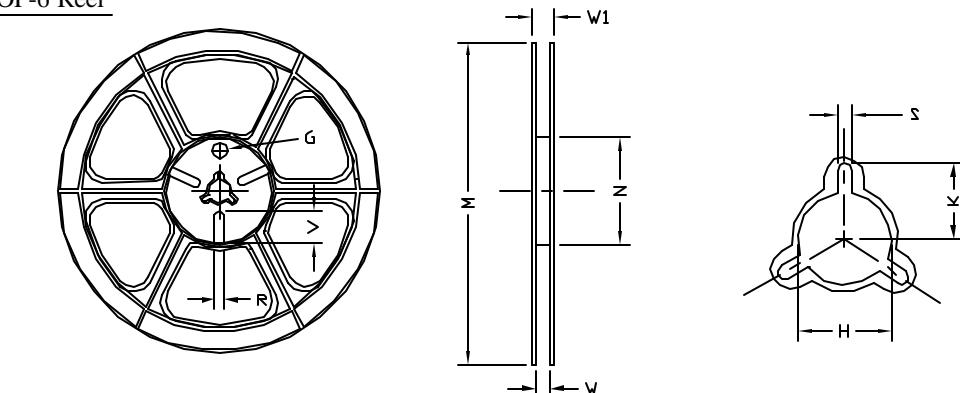
TSOP-6 Carrier Tape



UNIT: MM

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SOT-23 (8 mm)	3.15 ± 0.10	3.27 ± 0.10	1.34 ± 0.10	1.10 ± 0.01	1.50 ± 0.10	8.00 ± 0.20	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	0.25 ± 0.05

TSOP-6 Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
8 mm	Ø180	Ø180.00 ± 0.50	Ø60.50	9.00 ± 0.30	11.40 ± 1.00	Ø13.00 ± 0.50 -0.20	10.60	2.00 ± 0.50	Ø9.00	5.00	18.00

TSOP-6 Tape

Leader / Trailer
& Orientation

